

Fabrication of Suspended SiNWs



SiNW by One-Step Etching Route (This Work)





Electrical Characteristics



Radiation Effects on SiNW GAA FETs



Optimization of SiNW GAA FETs





Process Flow of SiNW GAA FETs



- Bulk substrate Suspended SiNW by one-step etching route
- Sacrificial oxidation
- Oxide dep. and CMP Partial oxide etching (STI)
- Thermal oxidation
- *in-situ* n+ poly-Si dep.
- Poly-Si CMP and HM dep.
- Gate patterning
- Spacer formation
- S/D implantation
- RTA and H_2 annealing



ວວ_{initial} сu Suppressed total ionizing dose (TID) effects **10**⁻⁹ Drain **Original GAA FETs Junction-modified GAA FETs** ΔV_{TH} - 60 mV - 0.2 mV **10**⁻ -0.6 -0.3 -0.9 0.0 0.3 -1.2 ⊿SS 10.9 mV/dec 3.3 mV/dec Gate voltage, V_{a} (V)

Conclusions

- An one-step plasma etching route was developed to form a suspended silicon nanowire on a bulk substrate.
- A gate-all-around field-effect transistor was fabricated and characterized for radiation hardening applications.
- The fabricated devices showed stronger radiation-tolerance than the double-gate MOSFETs due to the **separation between the channel and the isolation oxide**.
- The role of the gate spacer on TID effects was observed and verified through the overlapped junction profile.